

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Sheet 1 of 4

Complete if Known

Application Number	09/874,631
Filing Date	June 5, 2001
First Named Inventor	Moon et al.
Group Art Unit	2815
Examiner Name	S. Clark
Attorney Docket Number	2269-4368US (99-0959.00/US)

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
<i>SW</i>		US-3,239,496	03/1966	Jursich	
<i>SW</i>		US- 4,074,342	02/1978	Honn et al.	
<i>SW</i>		US- 4,818,728	04/1989	Rai et al.	
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<i>SW</i>		US- 5,404,044	04/1995	Booth et al.	
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<i>SW</i>		US- 5,742,100	04/1998	Schroeder et al.	
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Examiner Initials *	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁴
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
<i>SW</i>		EP 0684644	11.1995	Kata et al.		
<i>SW</i>		EP 1009027	06/2000	Okuno		
<i>SW</i>		KR 2001054744	07/2001	Choi et al. (English Abstract)		

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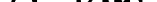
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				Attorney Docket Number	2269-4368US (99-0959.00/US)
Sheet	2	of	4		

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		Number - Kind Code ² (if known)			
GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL GVL		US- 6,232,666	05/2001	Corisis et al.	
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		US- 6,482,676	11/2002	Tsunoi et al.	
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	US- 2003/0134450 A1	07/2003	Lee		

[illegible]

Examiner Signature 	Date Considered	11/27/04
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Group Art Unit	2815
Examiner Name	S. Clark
Attorney Docket Number	2269-4368US (99-0959 00/US)

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
gk		AL-SARAWI et al., "A review of 3-D packaging technology," Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging, Vol 21, Issue 1, Feb. 1998, pp. 2-14.	
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gk		CLOT et al., "Flip-Chip on Flex for 3D Packaging," 1999. 24th IEEE/CPMT, 18-19 Oct. 1999, pp. 36-41.	
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gk		HATANAKA, H., "Packaging processes using flip chip bonder and future directions of technology development," Electronics Packaging Technology Conference, 2002. 4th, 10-12, Dec. 2002, pp. 434-439.	
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gk		LEE et al., "Enhancement of Moisture Sensitivity Performance of a FBGA," Proceedings of International Symposium on Electronic Materials & Packaging, 2000, pp. 470-475.	
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Examiner Name	S. Clark
Attorney Docket Number	2269-43681US (99-0959 00/1US)

OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
gml		LYONS et al., "A New Approach to Using Anisotropically Conductive Adhesives for Flip-Chip Assembly, Part A," <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology</i> , Vol. 19, Issue 1, March 1996, pp. 5-11.	
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